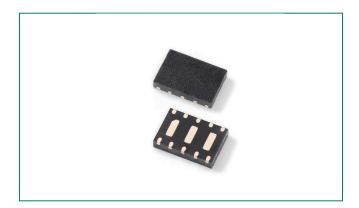
### TVS Diode Arrays (SPA®Diodes)

Lightning Surge Protection - AQ2555NUTG

### AQ2555NUTG 2.5V 45A Diode Array



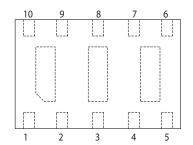


#### **Description**

The AQ2555NUTG is a low-capacitance, TVS Diode Array designed to provide protection against ESD (electrostatic discharge), CDE (cable discharge events), EFT (electrical fast transients), and lightning induced surges for high-speed, differential data lines. It's packaged in a  $\mu$ DFN package (3.0 x 2.0mm) and each component can protect up 4 channels or 2 differential pairs, up to 45A (IEC 61000-4-5 2<sup>nd</sup> edition,) and up to 30kV ESD (IEC 61000-4-2). The "flow-through" design minimizes signal distortion, reduces voltage overshoot, and provides a simplified PCB design.

The AQ2555NUTG with its low capacitance and low clamping voltage makes it ideal for high-speed data interfaces such as 1GbE applications found in notebooks, switches, etc.

#### **Pinout**

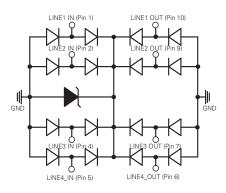


#### **Features**

- ESD, IEC 61000-4-2, ±30kV contact, ±30kV air
- EFT, IEC 61000-4-4, 50A (5/50ns)
- Lightning, IEC 61000-4-5 2<sup>nd</sup> edition, 45A (t<sub>n</sub>=8/20µs)
- Low capacitance of 2.5pF@0V (TYP) per I/O
- Low leakage current of 0.1µA (TYP) at 2.5V

- µDFN-10 package is optimized for high-speed data line routing
- Provides protection for two differential data pairs (4 channels) up to 45A
- Low operating and clamping voltage
- AEC-Q101 qualified
- Halogen free, Lead free and RoHS compliant
- Moisture Sensitivity Level(MSL -1)

#### **Functional Block Diagram**



#### **Applications**

- •10/100/1000 Ethernet
- WAN/LAN Equipment
- Desktops, Servers and Notebooks
- LVDS Interfaces
- Integrated Magnetics

#### **Application Example**

### 

Life Support Note:

#### Not Intended for Use in Life Support or Life Saving Applications

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

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Specifications are subject to change without notice

# TVS Diode Arrays (SPA®Diodes)

### Lightning Surge Protection - AQ2555NUTG

#### **Absolute Maximum Ratings**

Symbol	Parameter	Value	Units	
I <sub>PP</sub>	Peak Current (t <sub>p</sub> =8/20µs)	45	А	
P <sub>Pk</sub>	Peak Pulse Power (t <sub>p</sub> =8/20µs)	1000	W	
T <sub>OP</sub>	Operating Temperature	-40 to 150	°C	
T <sub>STOR</sub>	Storage Temperature	-55 to 150	°C	

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the component. This is a stress only rating and operation of the component at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### Electrical Characteristics (T<sub>OP</sub>=25°C)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units	
Reverse Standoff Voltage	V <sub>RWM</sub>	I <sub>R</sub> ≤ 1μA			2.5	V	
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> = 2.5V, T = 25°C		0.1	0.5	μΑ	
Snap Back Voltage	V <sub>SB</sub>	I <sub>SB</sub> = 50mA	2.0			V	
		$I_{pp} = 1A$ , $t_p = 8/20\mu s$ , Any I/O to Ground		4.5			
	V <sub>c</sub>	$I_{pp} = 10A$ , $t_p = 8/20\mu s$ , Any I/O to Ground		7.5		V	
Clamp Voltage		$I_{pp} = 25A$ , $t_p = 8/20\mu s$ , Any I/O to Ground		12			
olamp rollage		I <sub>pp</sub> = 45A, t <sub>p</sub> = 8/20μs, Line-to-Line <sup>1</sup> , two I/O Pins connected together on each line		19			
Dynamic Resistance <sup>2</sup>	R <sub>DYN</sub>	TLP, t <sub>p</sub> =100ns, Any I/O to Ground		0.1		Ω	
ESD Withstand Voltage V <sub>ESD</sub>		IEC 61000-4-2 (Contact)	±30			kV	
		IEC 61000-4-2 (Air)	±30			kV	
Diode Capacitance	C <sub>I/O to GND</sub>	Between I/O Pins and Ground $V_R = 0V$ , $f = 1MHz$		2.5		pF	
	C <sub>I/O to I/O</sub>	Between I/O Pins V <sub>R</sub> = 0V, f = 1MHz		1.2		pF	

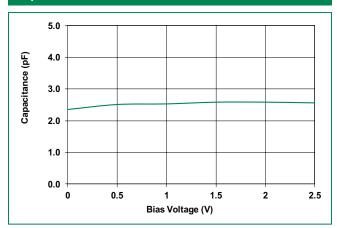
#### Notes:

<sup>1.</sup> Rating with 2 pins connected together per sugguested diagram (For example, pin1 is connected to pin 10, pin 2 is connected to Pin 9, Pin 4 is connected to pin 7 and pin 5 is connected to pin 6)

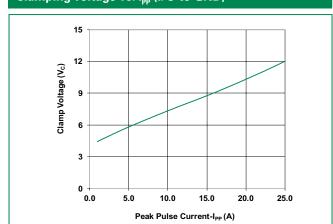
<sup>2.</sup> Transmission Line Pulse (TLP) with 100ns width, 2ns rise time, and average window t1=70ns to t2= 90ns



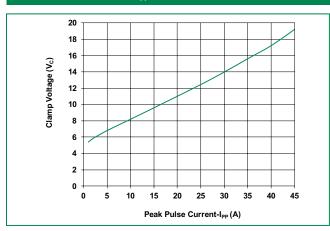
#### Capacitance vs. Reverse Bias



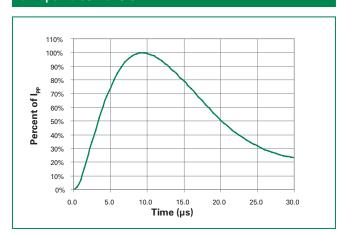
### Clamping Voltage vs. I<sub>PP</sub> (I/O to GND)



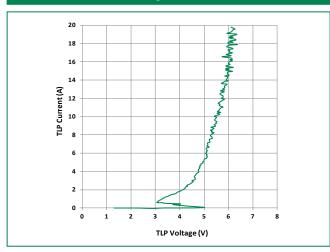
#### Clamping Voltage vs. I<sub>PP</sub> (Line-to-Line)



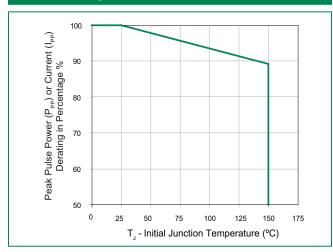
#### 8/20µs Pulse Waveform



#### Transmission Line Pulsing(TLP) Plot



#### **Power Derating Curve**

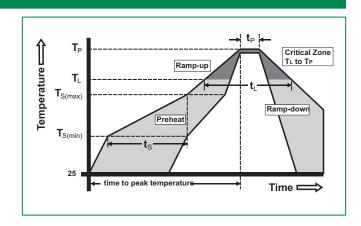


## TVS Diode Arrays (SPA®Diodes)

Lightning Surge Protection - AQ2555NUTG

#### **Soldering Parameters**

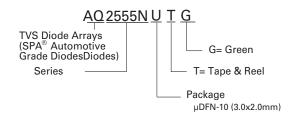
ndition	Pb – Free assembly	
-Temperature Min (T <sub>s(min)</sub> )	150°C	
-Temperature Max (T <sub>s(max)</sub> )	200°C	
-Time (min to max) (t <sub>s</sub> )	60 - 180 secs	
mp up rate (Liquidus) Temp (T <sub>L</sub> )	3°C/second max	
- Ramp-up Rate	3°C/second max	
-Temperature (T <sub>L</sub> ) (Liquidus)	217°C	
-Temperature (t <sub>L</sub> )	60 - 150 seconds	
erature (T <sub>P</sub> )	260 <sup>+0/-5</sup> °C	
n 5°C of actual peak re (t <sub>p</sub> )	20 – 40 seconds	
n Rate	6°C/second max	
to peak Temperature (T <sub>P</sub> )	8 minutes Max.	
eed	260°C	
	-Temperature Min (T <sub>s(min)</sub> ) -Temperature Max (T <sub>s(max)</sub> ) -Time (min to max) (t <sub>s</sub> ) mp up rate (Liquidus) Temp (T <sub>L</sub> ) -Ramp-up Rate -Temperature (T <sub>L</sub> ) (Liquidus) -Temperature (t <sub>L</sub> ) erature (T <sub>P</sub> ) n 5°C of actual peak re (t <sub>p</sub> ) n Rate to peak Temperature (T <sub>P</sub> )	



#### **Ordering Information**

Part Number	Package	Marking	Min. Order Qty.
AQ2555NUTG	μDFN-10 (3.0x2.0mm)	AQ2555	3000

#### **Part Numbering System**

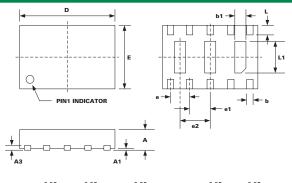


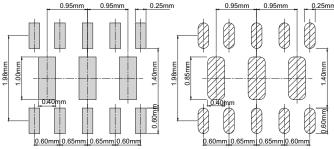
#### **Part Marking System**





#### Package Dimensions — µDFN-10 (3.0x2.0mm)





Recommended Soldering Pads Layout

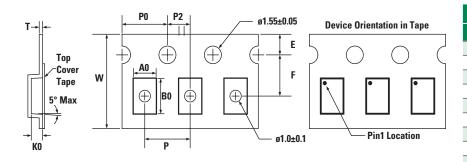
Recommended Stencil Apertures Recommended Stencil thickness 5mils

Package	μDFN-10 (3.0x2.0mm)						
JEDEC	MO-2			229			
Cumphal	Millimeters			Inches			
Symbol	Min	Nom	Max	Min	Nom	Max	
Α	0.50	0.60	0.65	0.020	0.024	0.026	
A1	0.00	0.03	0.05	0.000	0.001	0.002	
А3	0.15 Ref			0.006 Ref			
b	0.15	0.20	0.25	0.006	0.008	0.010	
b1	0.25	0.35	0.45	0.010	0.014	0.018	
D	2.90	3.00	3.10	0.114	0.118	0.122	
E	1.90	2.00	2.10	0.075	0.079	0.083	
е	0.60 BSC 0.024 BSC						
e1	0.65 BSC			0.026 BSC			
e2	0.95 BSC			0.037			
L	0.25 0.30 0.35 0.010 0.012		0.014				
L1	0.95	1.00	1.05	0.037	0.039	0.041	

#### Notes .

- 1. All dimensions are in millimeters
- 2. Dimensions include solder plating.
- 3. Dimensions are exclusive of mold flash & metal burn
- 4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
- 5. Package surface matte finish VDI 11-13.

#### Tape & Reel Specification — µDFN-10 (3.0x2.0mm)



μDFN-10 (3.0x2.0mm)		
Millimeters		
2.30 +/- 0.10		
3.20 +/- 0.10		
1.75 +/- 0.10		
3.50 +/- 0.05		
1.0 +/- 0.10		
4.00 +/- 0.10		
4.00 +/- 0.10		
2.00 +/- 0.10		
0.3 +/- 0.05		
8.00 +0.30/- 0.10		

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